

**描述 / Descriptions**

表面贴装肖特基整流二极管，反向电压：20V~200V，正向电流：3.0A，SMB封装。

Surface Mount Schottky Barrier Rectifiers, Reverse Voltage : 20 to 200V, Forward Current: 3.0A, SMB package.

特征 / Features

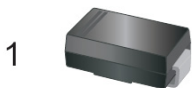
玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

用途 / Applications

一般用途。

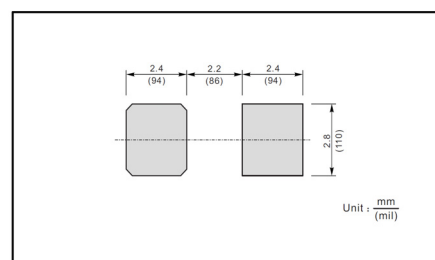
General purpose.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

2

PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size

**印章代码 / Marking**

见印章说明。See Marking Instructions.


极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating								单位 Unit
		SS32B	SS34B	SS36B	SS38B	SS310B	SS312B	SS315B	SS320B	
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F (AV)}	3.0								A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	80								A
Typical Junction Capacitance	C _j	450			400					pF
Typical Thermal Resistance ¹⁾	R _{θJA}	60								℃/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55~+150								℃

Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating								单位 Unit
			SS32B	SS34B	SS36B	SS38B	SS310B	SS312B	SS315B	SS320B	
Maximum Instantaneous Forward Voltage	V _F	I _F =3.0A	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I _R	T _a =25℃	0.5			0.3					mA
		T _a =100℃	5.0			3.0					mA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

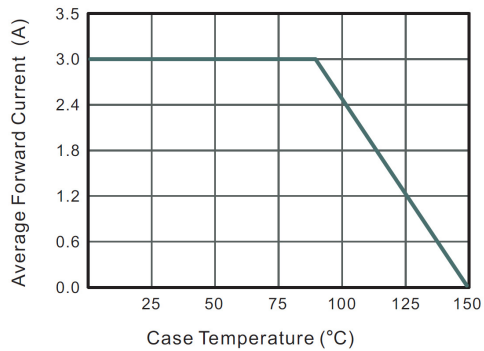


Fig.2 Typical Reverse Characteristics

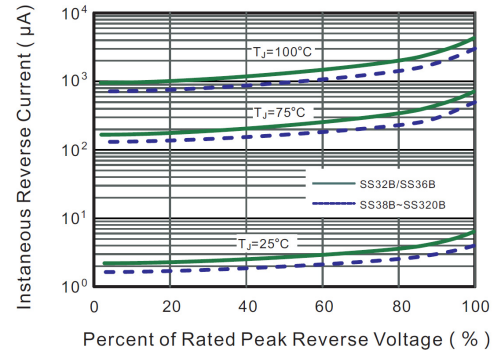


Fig.3 Typical Forward Characteristic

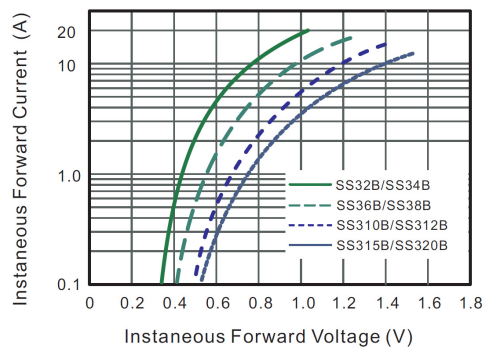


Fig.4 Typical Junction Capacitance

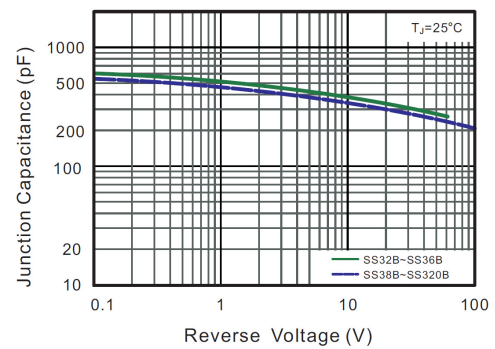


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

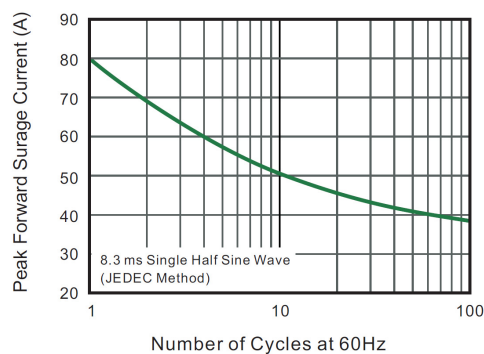
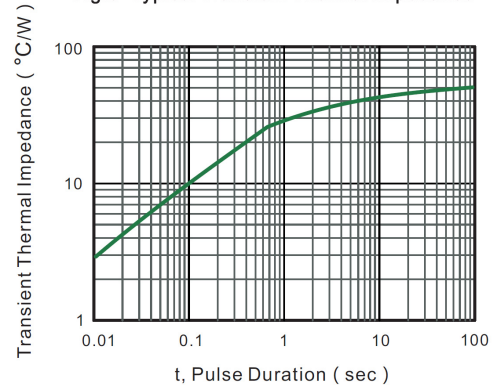
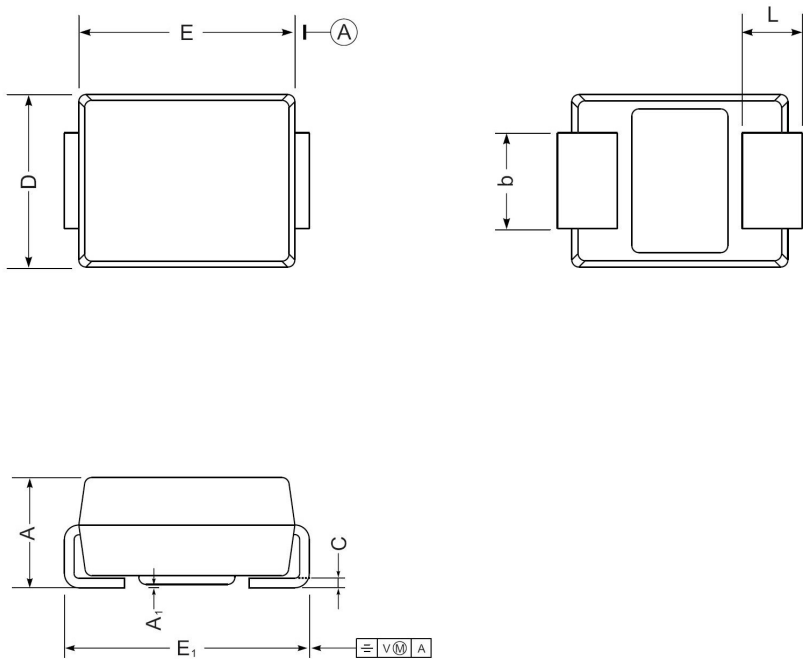


Fig.6- Typical Transient Thermal Impedance



外形尺寸图 / Package Dimensions

SMB



SMB mechanical data

UNIT		A	E	D	E ₁	A ₁	L	C	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	0.8	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75



Marking

Type number	Marking code
SS32B	SS32
SS34B	SS34
SS36B	SS36
SS38B	SS38
SS310B	SS310
SS312B	SS312
SS315B	SS315
SS320B	SS320



印章说明 / Marking Instructions



说明：

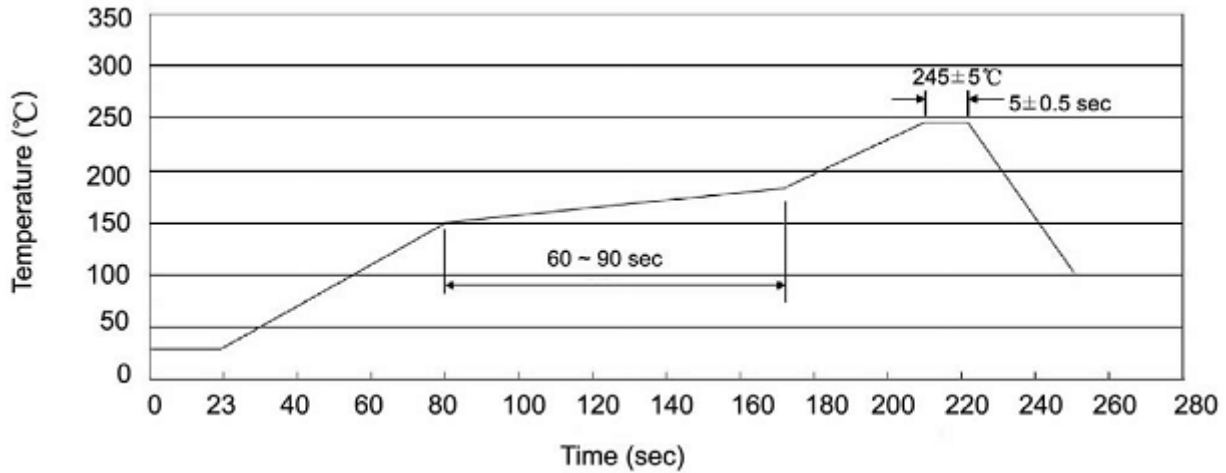
SS32： 为型号代码

****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

SS32： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMB	3000	5	15000	5	75000	7" ×11	185X180X105	390X385X205

使用说明 / Notices